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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	14-DIP (0.300", 7.62mm)
Supplier Device Package	14-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1825-i-p">https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1825-i-p</a>

**TABLE 1-2: PIC16(L)F1825 PINOUT DESCRIPTION (CONTINUED)**

Name	Function	Input Type	Output Type	Description
RC3/AN7/CPS7/C12IN3-/P2A <sup>(1,2)</sup> /CCP2 <sup>(1,2)</sup> /P1C <sup>(1,2)</sup> /SS1 <sup>(1,2)</sup> /MDMIN	RC3	TTL	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
	CPS7	AN	—	Capacitive sensing input 7.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	P2A	—	CMOS	PWM output.
	CCP2	AN	—	Capture/Compare/PWM2.
	P1C	—	CMOS	PWM output.
	SS1	ST	—	Slave Select input.
	MDMIN	ST	—	Modulator source input.
RC4/C2OUT/SRNQ/P1B/TX <sup>(1,2)</sup> /CK <sup>(1,2)</sup> /MDOUT	RC4	TTL	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
	SRNQ	—	CMOS	SR Latch inverting output.
	P1B	—	CMOS	PWM output.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	MDOUT	—	CMOS	Modulator output.
RC5/P1A/CCP1/DT <sup>(1,2)</sup> /RX <sup>(1,2)</sup> /MDCIN2	RC5	TTL	CMOS	General purpose I/O.
	P1A	—	CMOS	PWM output.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	MDCIN2	ST	—	Modulator Carrier Input 2.
VDD	VDD	Power	—	Positive supply.
VSS	VSS	Power	—	Ground reference.

**Legend:** AN = Analog input or output    CMOS = CMOS compatible input or output    OD = Open Drain  
TTL = TTL compatible input    ST = Schmitt Trigger input with CMOS levels    I<sup>2</sup>C™ = Schmitt Trigger input with I<sup>2</sup>C levels  
HV = High Voltage    XTAL = Crystal

**Note 1:** Pin functions can be moved using the APFCON0 or APFCON1 register.

**2:** Default function location.

**TABLE 1-3: PIC16(L)F1829 PINOUT DESCRIPTION (CONTINUED)**

Name	Function	Input Type	Output Type	Description
RA5/CLKIN/OSC1/T1OSI/SD02 <sup>(1)</sup> /T1CKI/P2A <sup>(1)</sup> /CCP2 <sup>(1)</sup>	RA5	TTL	CMOS	General purpose I/O.
	CLKIN	CMOS	—	External clock input (EC mode).
	OSC1	XTAL	—	Crystal/Resonator (LP, XT, HS modes).
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
	SD02	—	CMOS	SPI data output 2.
	T1CKI	ST	—	Timer1 clock input.
	P2A	—	CMOS	PWM output.
RB4/AN10/CPS10/SDA1/SDI1	CCP2	ST	CMOS	Capture/Compare/PWM2.
	RB4	TTL	CMOS	General purpose I/O.
	AN10	AN	—	A/D Channel 10 input.
	CPS10	AN	—	Capacitive sensing input 10.
	SDA1	I <sup>2</sup> C	OD	I <sup>2</sup> C™ data input/output.
RB5/AN11/CPS11/RX <sup>(1,2)</sup> /DT <sup>(1,2)</sup> /SDA2/SDI2	SDI1	CMOS	—	SPI data input.
	RB5	TTL	CMOS	General purpose I/O.
	AN11	AN	—	A/D Channel 11 input.
	CPS11	AN	—	Capacitive sensing input 11.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	SDA2	I <sup>2</sup> C	OD	I <sup>2</sup> C data input/output 2.
RB6/SCL1/SCK1	SDI2	CMOS	—	SPI data input 2.
	RB6	TTL	CMOS	General purpose I/O.
	SCL1	I <sup>2</sup> C	OD	I <sup>2</sup> C™ clock 1.
RB7/TX <sup>(1,2)</sup> /CK <sup>(1,2)</sup> /SCL2/SCK2	SCK1	ST	CMOS	SPI clock 1.
	RB7	TTL	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	SCL2	I <sup>2</sup> C	OD	I <sup>2</sup> C™ clock 2.
RC0/AN4/CPS4/C2IN+/P1D <sup>(1)</sup> /SS2 <sup>(1,2)</sup>	SCK2	ST	CMOS	SPI clock 2.
	RC0	TTL	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	CPS4	AN	—	Capacitive sensing input 4.
	C2IN+	AN	—	Comparator C2 positive input.
	P1D	—	CMOS	PWM output.
RC1/AN5/CPS5/C12IN1-/P1C <sup>(1)</sup> /SD02 <sup>(1,2)</sup>	SS2	ST	—	Slave Select input 2.
	RC1	TTL	CMOS	General purpose I/O.
	AN5	AN	—	A/D Channel 5 input.
	CPS5	AN	—	Capacitive sensing input 5.
	C12IN1-	AN	—	Comparator C1 or C2 negative input.
	P1C	—	CMOS	PWM output.
	SD02	—	CMOS	SPI data output 2.

**Legend:** AN = Analog input or output    CMOS = CMOS compatible input or output    OD = Open Drain  
TTL = TTL compatible input    ST = Schmitt Trigger input with CMOS levels    I<sup>2</sup>C™ = Schmitt Trigger input with I<sup>2</sup>C levels  
HV = High Voltage    XTAL = Crystal

**Note 1:** Pin functions can be moved using the APFCON0 or APFCON1 register.  
**2:** Default function location.

**TABLE 6-1: SUMMARY OF REGISTERS ASSOCIATED WITH REFERENCE CLOCK SOURCES**

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CLKRCON	CLKREN	CLKROE	CLKRSLR	CLKRDC<1:0>		CLKRDIV<2:0>			72

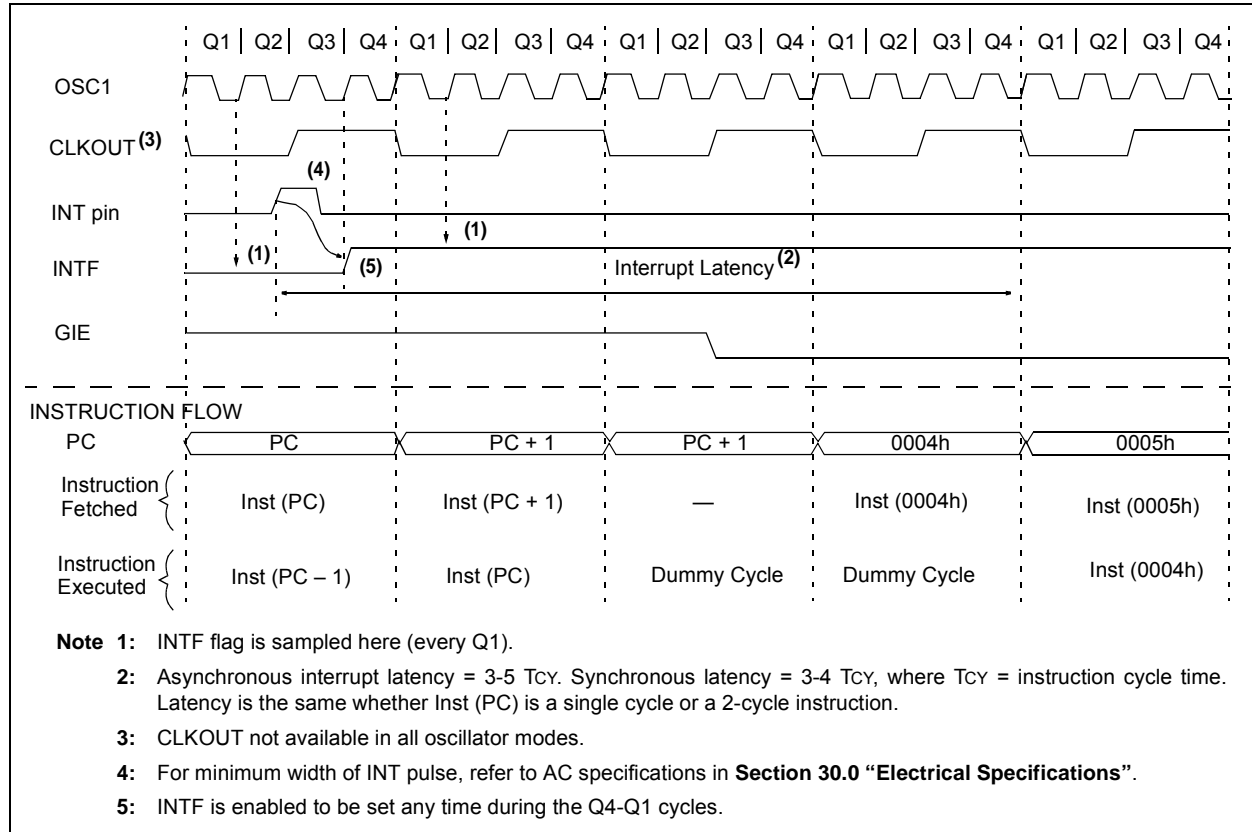
**Legend:** — Unimplemented locations read as '0'. Shaded cells are not used by reference clock sources.

**TABLE 6-2: SUMMARY OF CONFIGURATION WORD WITH REFERENCE CLOCK SOURCES**

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	IESO	CLKOUTEN	BOREN<1:0>		CPD	48
	7:0	CP	MCLRE	PWRTE	WDTE<1:0>		FOSC<2:0>			

**Legend:** — Unimplemented locations read as '0'. Shaded cells are not used by reference clock sources.

**FIGURE 8-3: INT PIN INTERRUPT TIMING**



## 11.0 DATA EEPROM AND FLASH PROGRAM MEMORY CONTROL

The data EEPROM and Flash program memory are readable and writable during normal operation (full  $V_{DD}$  range). These memories are not directly mapped in the register file space. Instead, they are indirectly addressed through the Special Function Registers (SFRs). There are six SFRs used to access these memories:

- EECON1
- EECON2
- EEDATL
- EEDATH
- EEADRL
- EEADRH

When interfacing the data memory block, EEDATL holds the 8-bit data for read/write, and EEADRL holds the address of the EEDATL location being accessed. These devices have 256 bytes of data EEPROM with an address range from 0h to 0FFh.

When accessing the program memory block, the EEDATH:EEDATL register pair forms a 2-byte word that holds the 14-bit data for read/write, and the EEADRL and EEADRH registers form a 2-byte word that holds the 15-bit address of the program memory location being read.

The EEPROM data memory allows byte read and write. An EEPROM byte write automatically erases the location and writes the new data (erase before write).

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump rated to operate over the voltage range of the device for byte or word operations.

Depending on the setting of the Flash Program Memory Self Write Enable bits  $WRT<1:0>$  of the Configuration Word 2, the device may or may not be able to write certain blocks of the program memory. However, reads from the program memory are always allowed.

When the device is code-protected, the device programmer can no longer access data or program memory. When code-protected, the CPU may continue to read and write the data EEPROM memory and Flash program memory.

## 11.1 EEADRL and EEADRH Registers

The EEADRH:EEADRL register pair can address up to a maximum of 256 bytes of data EEPROM or up to a maximum of 32K words of program memory.

When selecting a program address value, the MSB of the address is written to the EEADRH register and the LSB is written to the EEADRL register. When selecting a EEPROM address value, only the LSB of the address is written to the EEADRL register.

### 11.1.1 EECON1 AND EECON2 REGISTERS

EECON1 is the control register for EE memory accesses.

Control bit  $EEP_{GD}$  determines if the access will be a program or data memory access. When clear, any subsequent operations will operate on the EEPROM memory. When set, any subsequent operations will operate on the program memory. On Reset, EEPROM is selected by default.

Control bits  $RD$  and  $WR$  initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared in hardware at completion of the read or write operation. The inability to clear the  $WR$  bit in software prevents the accidental, premature termination of a write operation.

The  $WREN$  bit, when set, will allow a write operation to occur. On power-up, the  $WREN$  bit is clear. The  $WRERR$  bit is set when a write operation is interrupted by a Reset during normal operation. In these situations, following Reset, the user can check the  $WRERR$  bit and execute the appropriate error handling routine.

Interrupt flag bit  $EEIF$  of the  $PIR2$  register is set when write is complete. It must be cleared in the software.

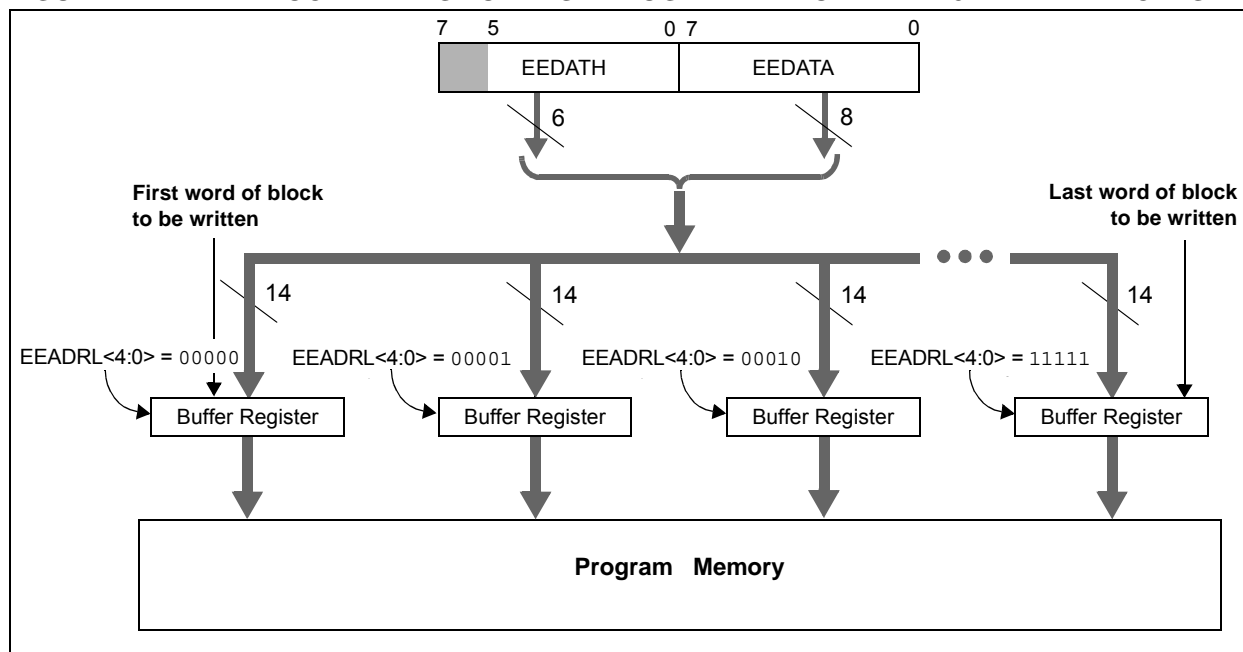
Reading  $EECON2$  will read all '0's. The  $EECON2$  register is used exclusively in the data EEPROM write sequence. To enable writes, a specific pattern must be written to  $EECON2$ .

# PIC16(L)F1825/9

After the "BSF EECON1,WR" instruction, the processor requires two cycles to set up the write operation. The user must place two NOP instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms, only during the cycle in which the write takes place (i.e., the last word of the block write). This is not Sleep mode as the clocks and peripherals will

continue to run. The processor does not stall when LWLO = 1, loading the write latches. After the write cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

**FIGURE 11-2: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES**



## 12.4 PORTC Registers

PORTC is a 6-bit wide (8-bit wide for PIC16(L)F1829), bidirectional port. The corresponding data direction register is TRISC (Register 12-16). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 12-2 shows how to initialize a port.

Reading the PORTC register (Register 12-15) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATC).

The TRISC register (Register 12-16) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

The INLVLC register (Register 12-20) controls the input voltage threshold for each of the available PORTC input pins. A selection between the Schmitt Trigger CMOS or the TTL Compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTC register and also the level at which an Interrupt-on-Change occurs, if that feature is enabled. See **Section 30.4 "DC Characteristics: PIC16(L)F1825/9-I/E"** for more information on threshold levels.

**Note:** Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin.

### 12.4.1 ANSEL register

The ANSEL register (Register 12-18) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSEL bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSEL bits has no effect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

**Note:** The ANSEL bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.



## REGISTER 19-1: CMxCON0: COMPARATOR Cx CONTROL REGISTER 0

R/W-0/0	R-0/0	R/W-0/0	R/W-0/0	U-0	R/W-1/1	R/W-0/0	R/W-0/0
CxON	CxOUT	CxOE	CxPOL	—	CxSP	CxHYS	CxSYNC
bit 7							bit 0

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

u = Bit is unchanged

x = Bit is unknown

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set

'0' = Bit is cleared

- bit 7 **CxON:** Comparator Enable bit  
 1 = Comparator is enabled  
 0 = Comparator is disabled and consumes no active power
- bit 6 **CxOUT:** Comparator Output bit  
If CxPOL = 1 (inverted polarity):  
 1 = CxVP < CxVN  
 0 = CxVP > CxVN  
If CxPOL = 0 (non-inverted polarity):  
 1 = CxVP > CxVN  
 0 = CxVP < CxVN
- bit 5 **CxOE:** Comparator Output Enable bit  
 1 = CxOUT is present on the CxOUT pin. Requires that the associated TRIS bit be cleared to actually drive the pin. Not affected by CxON.  
 0 = CxOUT is internal only
- bit 4 **CxPOL:** Comparator Output Polarity Select bit  
 1 = Comparator output is inverted  
 0 = Comparator output is not inverted
- bit 3 **Unimplemented:** Read as '0'
- bit 2 **CxSP:** Comparator Speed/Power Select bit  
 1 = Comparator operates in normal power, higher speed mode  
 0 = Comparator operates in low-power, low-speed mode
- bit 1 **CxHYS:** Comparator Hysteresis Enable bit  
 1 = Comparator hysteresis enabled  
 0 = Comparator hysteresis disabled
- bit 0 **CxSYNC:** Comparator Output Synchronous Mode bit  
 1 = Comparator output to Timer1 and I/O pin is synchronous to changes on Timer1 clock source. Output updated on the falling edge of Timer1 clock source.  
 0 = Comparator output to Timer1 and I/O pin is asynchronous.

**TABLE 21-5: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1**

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	123
CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				224
CCP2CON	P2M<1:0>		DC2B<1:0>		CCP2M<3:0>				224
INLVLA	—	—	INLVLA5	INLVLA4	INLVLA3	INLVLA2	INLVLA1	INLVLA0	124
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	87
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	88
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	92
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								181*
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								181*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	122
T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	T1SYNC	—	TMR1ON	185
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/ DONE	T1GVAL	T1GSS<1:0>		186

**Legend:** — Unimplemented location, read as '0'. Shaded cells are not used by the Timer1 module.  
 \* Page provides register information.

## REGISTER 23-3: MDCARH: MODULATION HIGH CARRIER CONTROL REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
MDCHODIS	MDCHPOL	MDCHSYNC	—	MDCH<3:0>			
bit 7				bit 0			

### Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

- bit 7 **MDCHODIS:** Modulator High Carrier Output Disable bit  
 1 = Output signal driving the peripheral output pin (selected by MDCH<3:0>) is disabled  
 0 = Output signal driving the peripheral output pin (selected by MDCH<3:0>) is enabled
- bit 6 **MDCHPOL:** Modulator High Carrier Polarity Select bit  
 1 = Selected high carrier signal is inverted  
 0 = Selected high carrier signal is not inverted
- bit 5 **MDCHSYNC:** Modulator High Carrier Synchronization Enable bit  
 1 = Modulator waits for a falling edge on the high time carrier signal before allowing a switch to the low time carrier  
 0 = Modulator Output is not synchronized to the high time carrier signal<sup>(1)</sup>
- bit 4 **Unimplemented:** Read as '0'
- bit 3-0 **MDCH<3:0>** Modulator Data High Carrier Selection bits <sup>(1)</sup>  
 1111 = Reserved. No channel connected.  
 •  
 •  
 •  
 1000 = Reserved. No channel connected.  
 0111 = CCP4 output (PWM Output mode only)  
 0110 = CCP3 output (PWM Output mode only)  
 0101 = CCP2 output (PWM Output mode only)  
 0100 = CCP1 output (PWM Output mode only)  
 0011 = Reference Clock module signal (CLKR)  
 0010 = MDCIN2 port pin  
 0001 = MDCIN1 port pin  
 0000 = Vss

**Note 1:** Narrowed carrier pulse widths or spurs may occur in the signal stream if the carrier is not synchronized.

## 25.6.4 I<sup>2</sup>C MASTER MODE START CONDITION TIMING

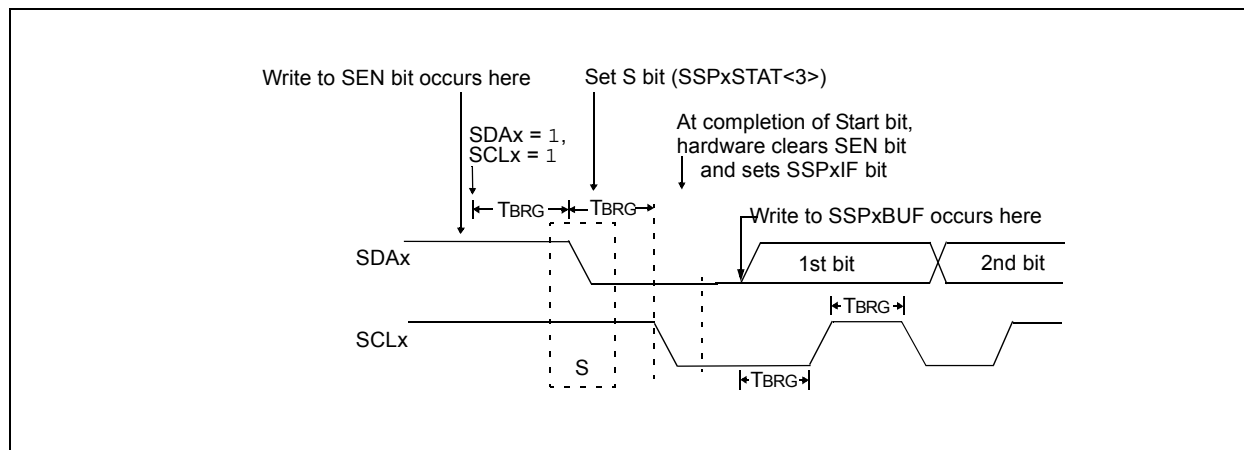
To initiate a Start condition (Figure 25-26), the user sets the Start Enable bit, SEN bit of the SSPxCON2 register. If the SDAx and SCLx pins are sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and starts its count. If SCLx and SDAx are both sampled high when the Baud Rate Generator times out (TBRG), the SDAx pin is driven low. The action of the SDAx being driven low while SCLx is high is the Start condition and causes the S bit of the SSPxSTAT1 register to be set. Following this, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and resumes its count. When the Baud Rate Generator times out (TBRG), the SEN bit of the SSPxCON2 register will be automatically cleared

by hardware; the Baud Rate Generator is suspended, leaving the SDAx line held low and the Start condition is complete.

**Note 1:** If at the beginning of the Start condition, the SDAx and SCLx pins are already sampled low, or if during the Start condition, the SCLx line is sampled low before the SDAx line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCLxIF, is set, the Start condition is aborted and the I<sup>2</sup>C module is reset into its Idle state.

**2:** The Philips I<sup>2</sup>C™ Specification states that a bus collision cannot occur on a Start.

**FIGURE 25-26: FIRST START BIT TIMING**



## DECFSZ Decrement f, Skip if 0

**Syntax:** `[label] DECFSZ f,d`

**Operands:**  $0 \leq f \leq 127$   
 $d \in [0,1]$

**Operation:**  $(f) - 1 \rightarrow (\text{destination});$   
skip if result = 0

**Status Affected:** None

**Description:** The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.

## INCFSZ Increment f, Skip if 0

**Syntax:** `[label] INCFSZ f,d`

**Operands:**  $0 \leq f \leq 127$   
 $d \in [0,1]$

**Operation:**  $(f) + 1 \rightarrow (\text{destination});$   
skip if result = 0

**Status Affected:** None

**Description:** The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

## GOTO Unconditional Branch

**Syntax:** `[label] GOTO k`

**Operands:**  $0 \leq k \leq 2047$

**Operation:**  $k \rightarrow PC<10:0>$   
 $PCLATH<6:3> \rightarrow PC<14:11>$

**Status Affected:** None

**Description:** GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

## IORLW Inclusive OR literal with W

**Syntax:** `[label] IORLW k`

**Operands:**  $0 \leq k \leq 255$

**Operation:**  $(W) .OR. k \rightarrow (W)$

**Status Affected:** Z

**Description:** The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.

## INCF Increment f

**Syntax:** `[label] INCF f,d`

**Operands:**  $0 \leq f \leq 127$   
 $d \in [0,1]$

**Operation:**  $(f) + 1 \rightarrow (\text{destination})$

**Status Affected:** Z

**Description:** The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

## IORWF Inclusive OR W with f

**Syntax:** `[label] IORWF f,d`

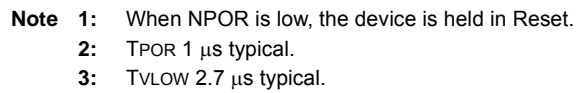
**Operands:**  $0 \leq f \leq 127$   
 $d \in [0,1]$

**Operation:**  $(W) .OR. (f) \rightarrow (\text{destination})$

**Status Affected:** Z

**Description:** Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

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# PIC16(L)F1825/9

## 30.3 DC Characteristics: PIC16(L)F1825/9-I/E (Power-Down)

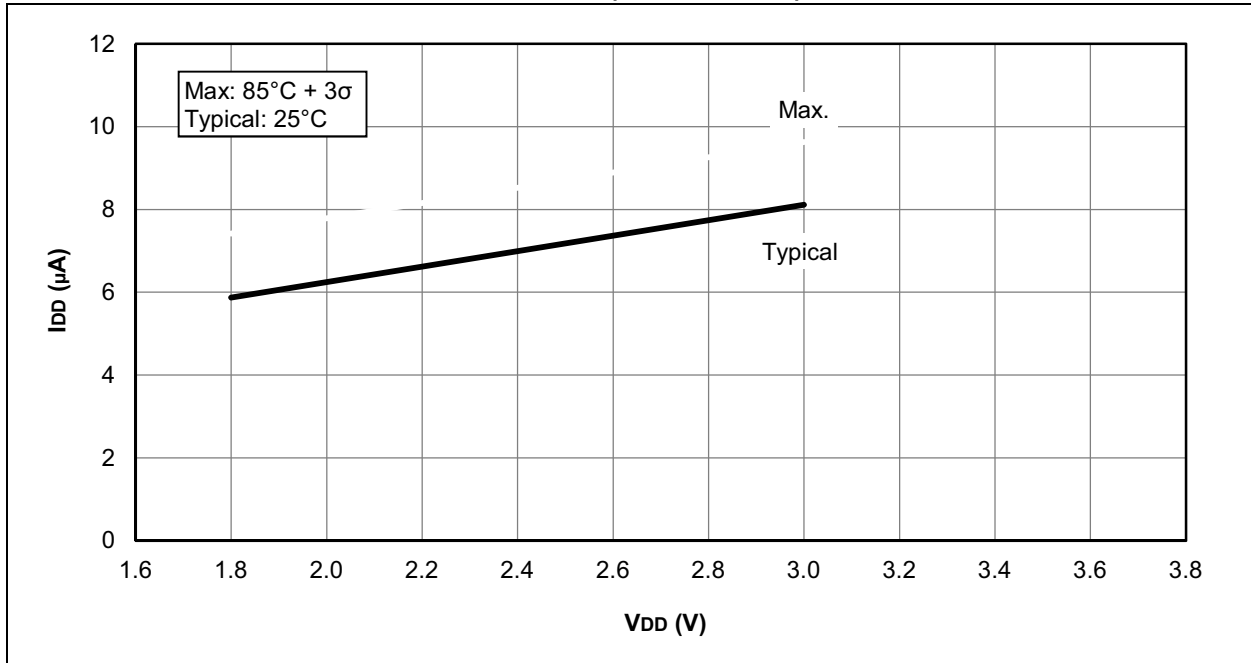
PIC16LF1825/9			Standard Operating Conditions (unless otherwise stated)					
			Operating temperature    -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F1825/9			Standard Operating Conditions (unless otherwise stated)					
			Operating temperature    -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
D022	Power-down Base Current (IPD) <sup>(2)</sup>							
		—	0.02	1.0	2.7	μA	1.8	WDT, BOR, FVR, and T1OSC disabled, all Peripherals Inactive
		—	0.05	1.75	3.3	μA	3.0	
D022		—	17.8	37	44	μA	1.8	WDT, BOR, FVR, and T1OSC disabled, all Peripherals Inactive
		—	20.5	42	48	μA	3.0	
		—	21.7	45	65	μA	5.0	
D023		—	0.3	1.5	3.0	μA	1.8	LPWDT Current (Note 1)
		—	0.5	2.0	3.7	μA	3.0	
D023		—	18	38	44	μA	1.8	LPWDT Current (Note 1)
		—	20.9	43	48	μA	3.0	
		—	22.1	48	65	μA	5.0	
D023A		—	12.6	22	25	μA	1.8	FVR current (Note 1)
		—	12.8	24	27	μA	3.0	
D023A		—	32.7	62	65	μA	1.8	FVR current (Note 1)
		—	39	72	75	μA	3.0	
		—	69	115	120	μA	5.0	
D024		—	7	14	16	μA	3.0	BOR Current (Note 1)
D024		—	24	47	50	μA	3.0	BOR Current (Note 1)
		—	27	55	70	μA	5.0	
D025		—	0.65	4.5	5	μA	1.8	T1OSC Current (Note 1)
		—	1.3	5	5.5	μA	3.0	
D025		—	19	39	45	μA	1.8	T1OSC Current (Note 1)
		—	21.6	42	65	μA	3.0	
		—	23	47	52	μA	5.0	
D026		—	0.05	1.5	3.0	μA	1.8	A/D Current (Note 1, 3), no conversion in progress
		—	0.07	2.0	3.5	μA	3.0	
D026		—	17.8	38	45	μA	1.8	A/D Current (Note 1, 3), no conversion in progress
		—	21	45	50	μA	3.0	
		—	22	50	65	μA	5.0	

\* These parameters are characterized but not tested.

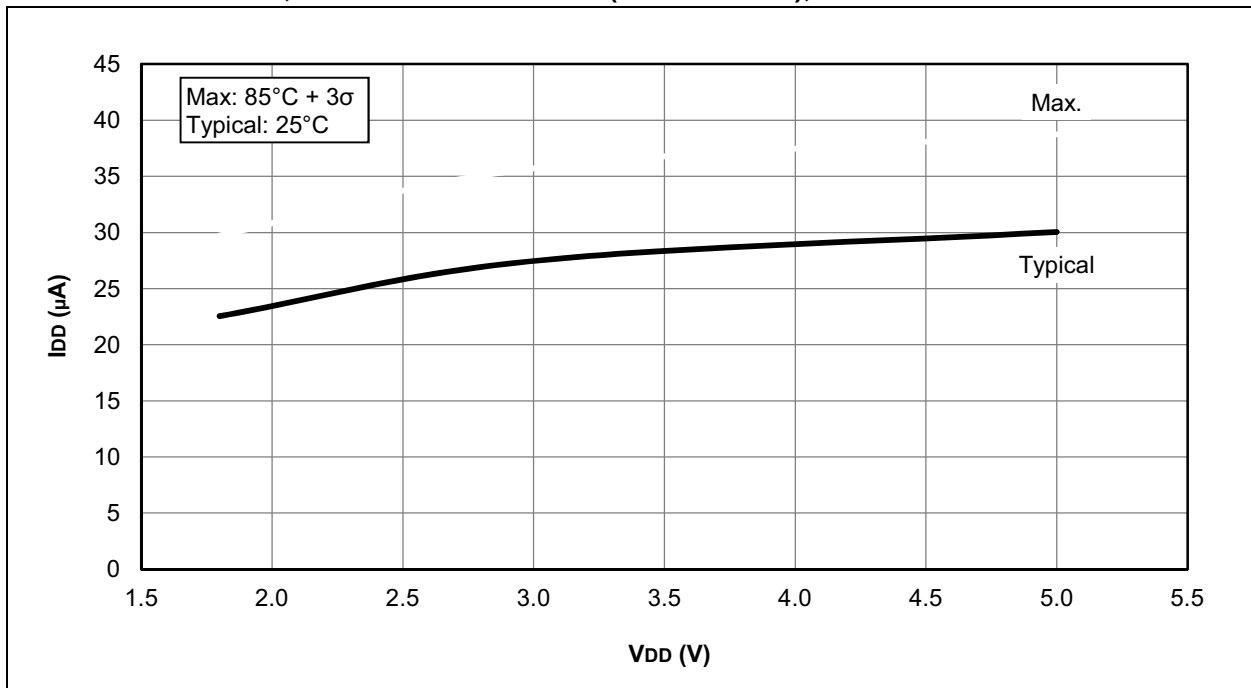
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.
- Note 2:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.
- Note 3:** A/D oscillator source is FRC.

**FIGURE 31-1:  $I_{DD}$ , LP OSCILLATOR MODE ( $F_{osc} = 32$  kHz), PIC16LF1825/9 ONLY**



**FIGURE 31-2:  $I_{DD}$ , LP OSCILLATOR MODE ( $F_{osc} = 32$  kHz), PIC16F1825/9 ONLY**





# PIC16(L)F1825/9

FIGURE 31-23: I<sub>PD</sub>, WATCHDOG TIMER (WDT), PIC16LF1825/9 ONLY

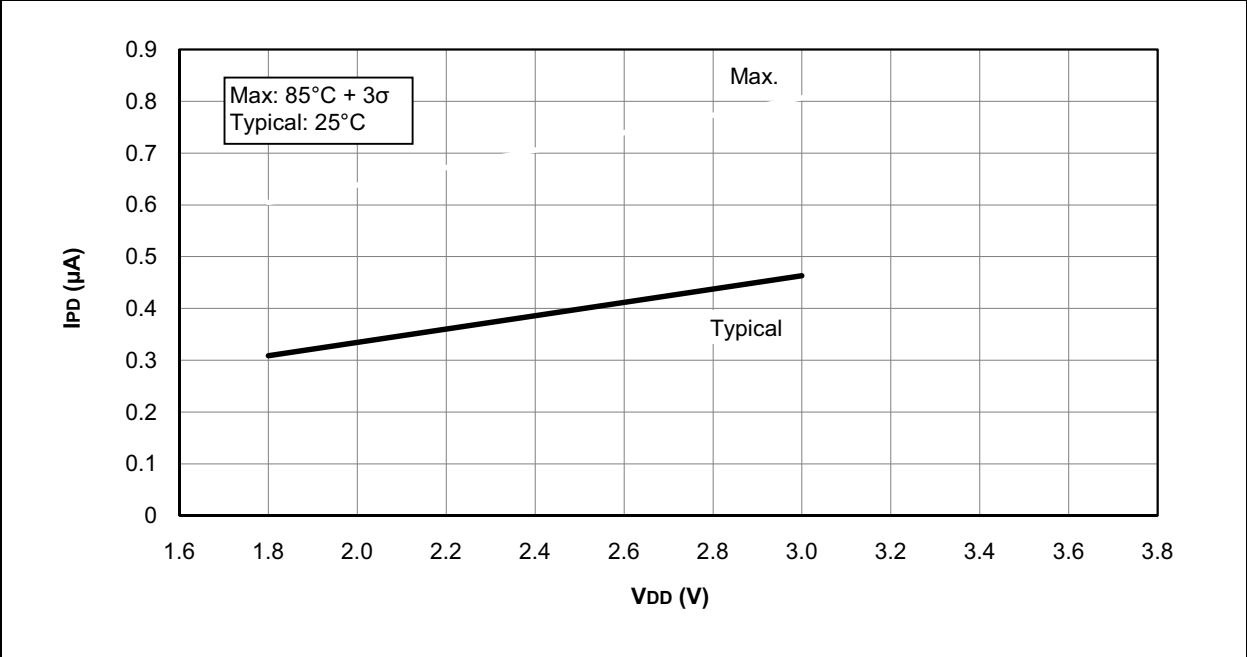
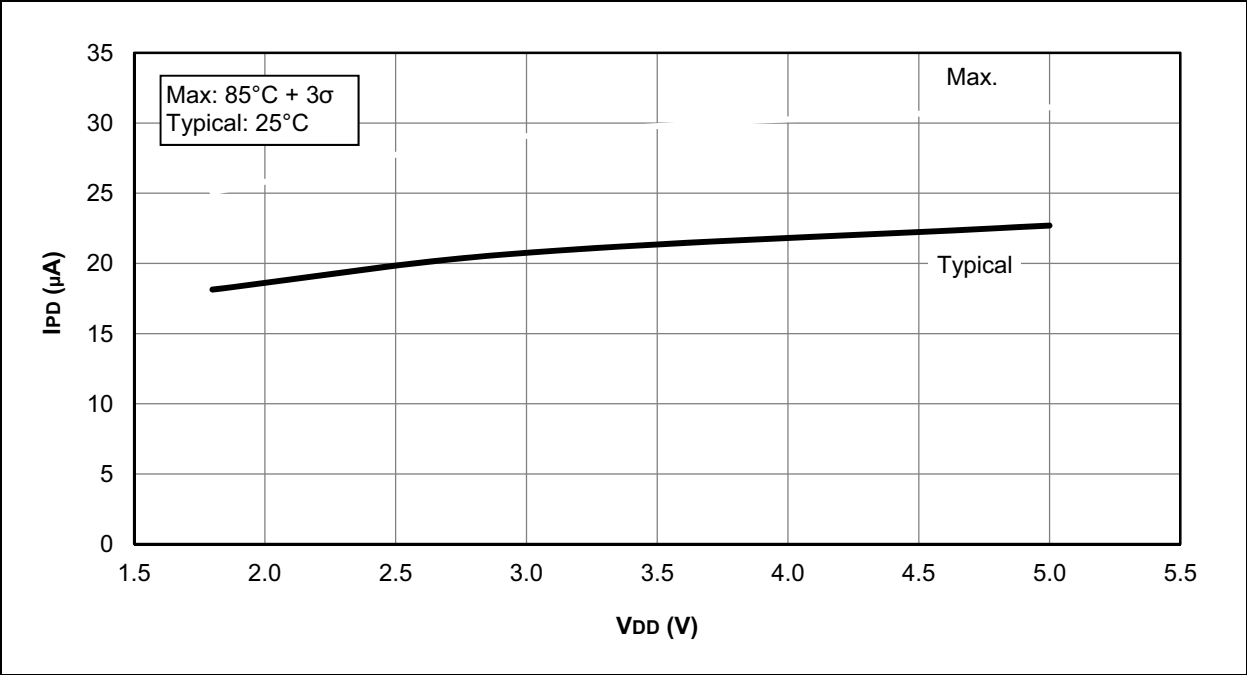
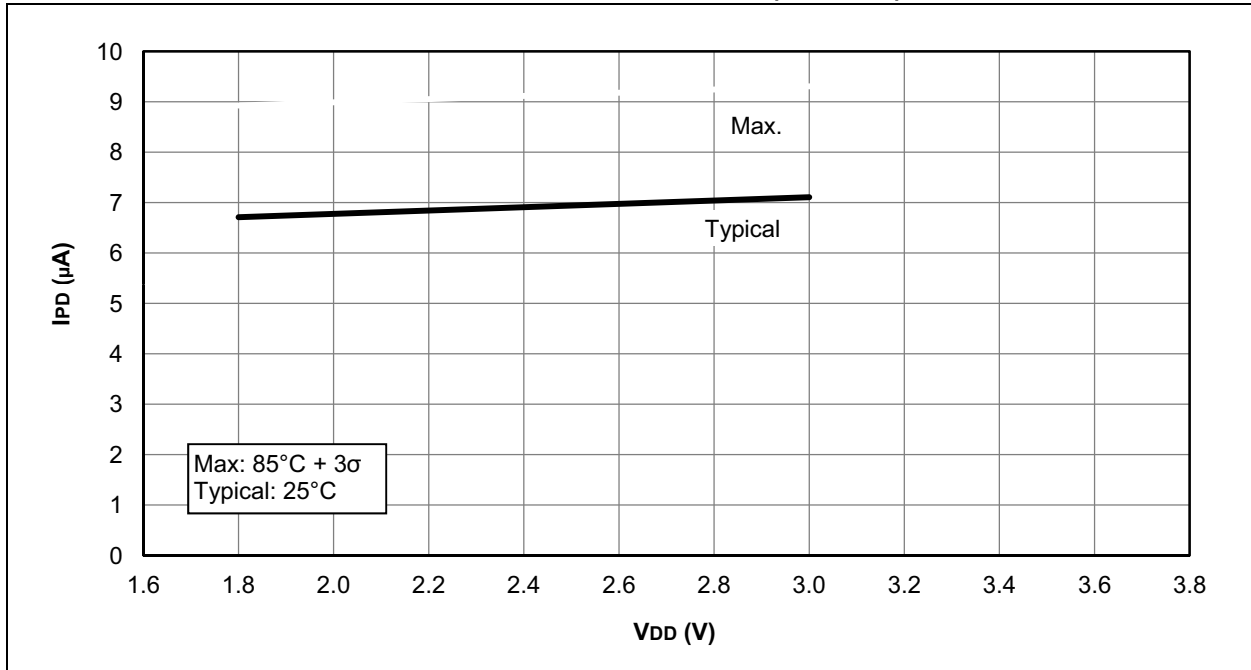


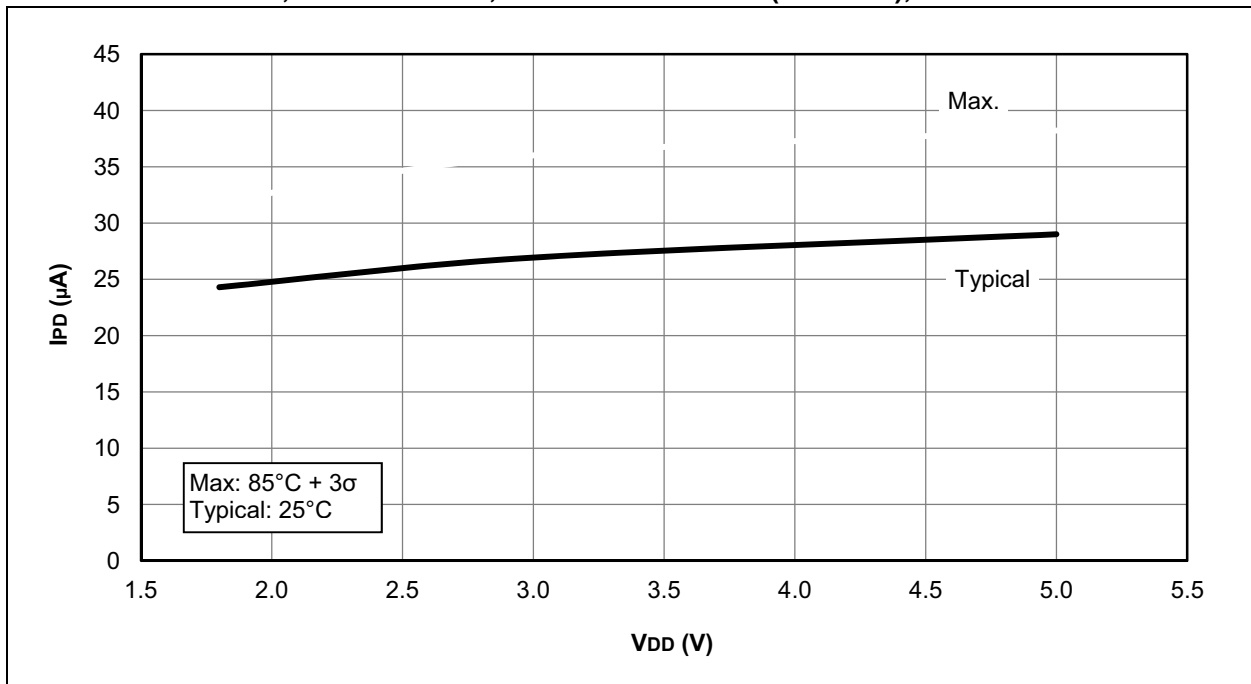
FIGURE 31-24: I<sub>PD</sub>, WATCHDOG TIMER (WDT), PIC16F1825/9 ONLY



**FIGURE 31-37:  $I_{PD}$ , COMPARATOR, LOW-POWER MODE ( $CxSP = 0$ ), PIC16LF1825/9 ONLY**

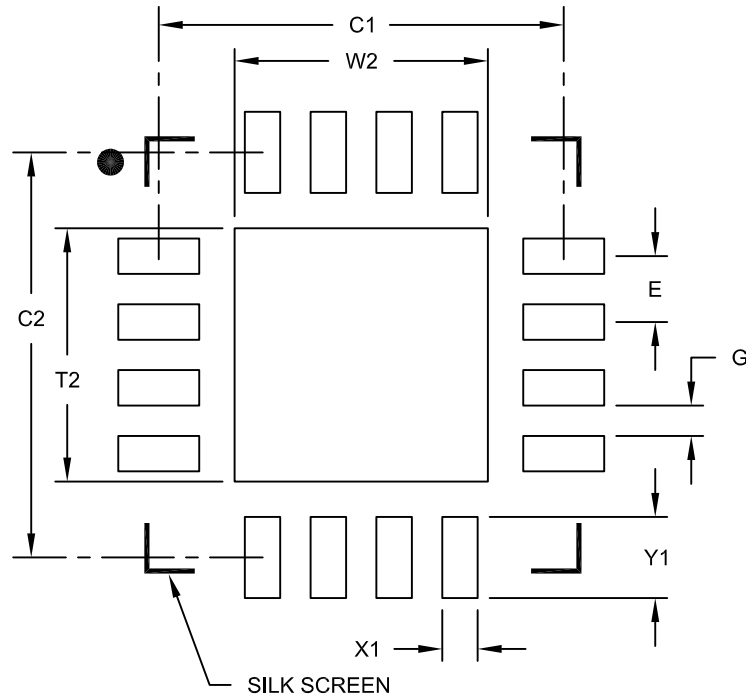


**FIGURE 31-38:  $I_{PD}$ , COMPARATOR, LOW-POWER MODE ( $CxSP = 0$ ), PIC16F1825/9 ONLY**



## 16-Lead Plastic Quad Flat, No Lead Package (ML) - 4x4x0.9mm Body [QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			2.50
Optional Center Pad Length	T2			2.50
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X16)	X1			0.35
Contact Pad Length (X16)	Y1			0.80
Distance Between Pads	G	0.30		

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

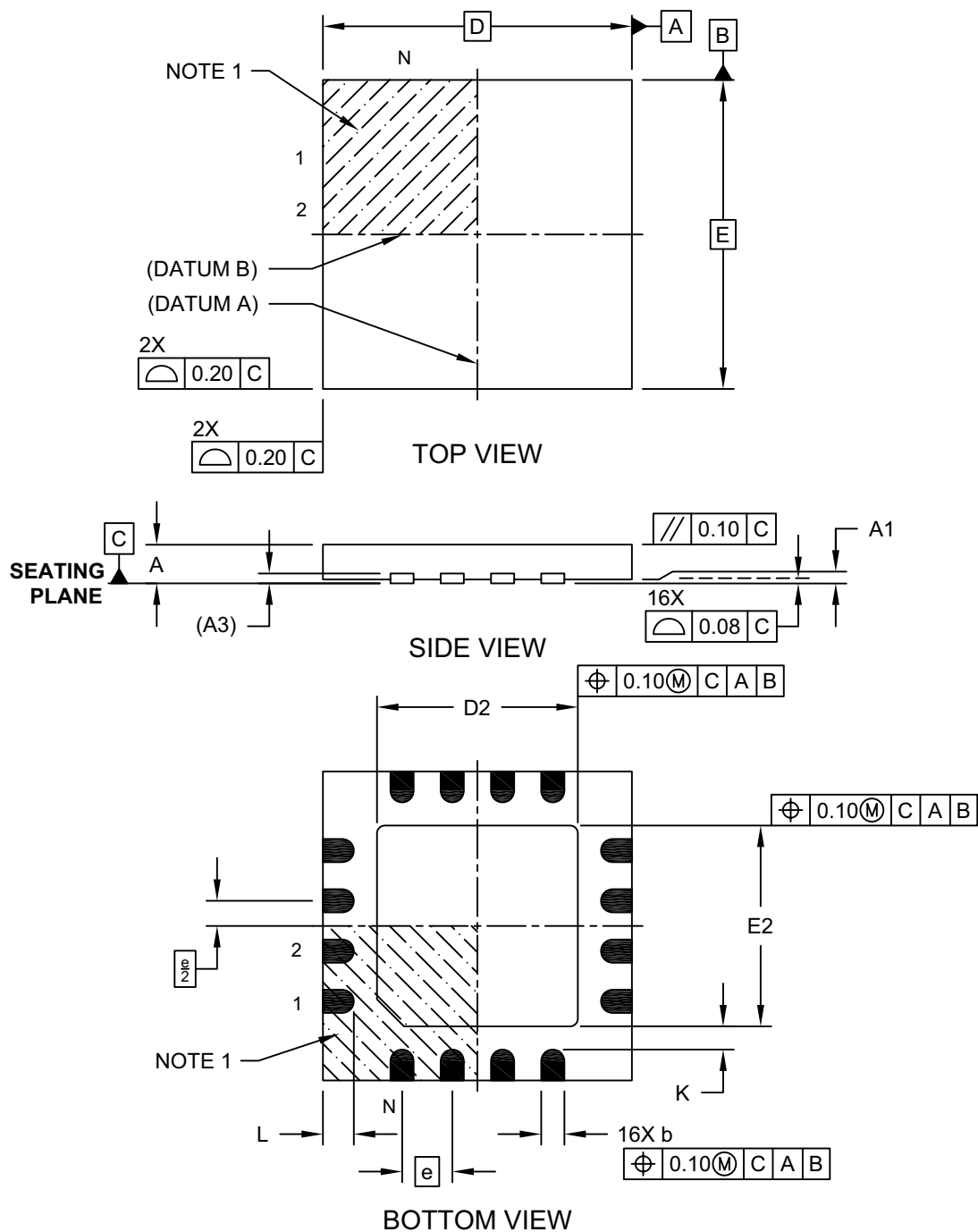
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2127A

# PIC16(L)F1825/9

## 16-Lead Ultra Thin Plastic Quad Flat, No Lead Package (JQ) - 4x4x0.5 mm Body [UQFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-257A Sheet 1 of 2

# PIC16(L)F1825/9

## APPENDIX A: DATA SHEET REVISION HISTORY

### Revision A (08/2010)

Original release.

### Revision B (05/2011)

Revised Electrical Specifications.

### Revision C (06/2012)

Updated the Family Types table; Updated Figures 1, 2 and 3; Updated Table 3-3; Changed all instances of SDO into SDO1, SDOSEL into SDO1SEL and SSSEL into SS1SEL; Added PIR3, PIR4, PIE3 and PIE4 to Table 3-3; Updated Register 4-2; Updated Sections 5.2.2.5 and 5.5.3; Added Note 1 to Table 11-3; Updated Figure 13-1 and Equation 16-1; Updated Section 19.9; Added charts to the DC and AC Characteristics Graphs section; Revised the Electrical Specifications section; Updated the Packaging Information section; Updated the Product Identification System section; Other minor corrections.

### Revision D (05/2014)

Added new UQFN packages: 16-Lead, UQFN, 4x4x0.5, (JQ) and 20-Lead, UQFN, 4x4x0.5, (GZ) packages. Minor corrections.

### Revision E (4/2015)

Added Section 30.9: High Temperature Operation in the Electrical Specifications section.

## APPENDIX B: MIGRATING FROM OTHER PIC® DEVICES

This shows a comparison of features in the migration from the PIC16F648 device to the PIC16(L)F1825/9 family of devices.

This section provides comparisons when migrating from other similar PIC® devices to the PIC16(L)F1825/9 family of devices.

### B.1 PIC16F648A to PIC16F1825/9

TABLE B-1: FEATURE COMPARISON

Feature	PIC16F648A	PIC16F1825/9
Max. Operating Speed	20 MHz	32 MHz
Max. Program Memory (Words)	4K	8K
Max. SRAM (Bytes)	256	1024
Max. EEPROM (Bytes)	256	256
A/D Resolution	10-bit	10-bit
Timers (8/16-bit)	2/1	4/1
Brown-out Reset	Y	Y
Internal Pull-ups	RB<7:0>	PIC16F1825: RA<5:0>, RC<5:0> PIC16F1829: RA<5:0>, RB<7:4>, RC<7:0>
Interrupt-on-change	RB<7:4>	PIC16F1825: RA<5:0>, Edge Selectable PIC16F1829: RA<5:0>, RB<7:4>, Edge Selectable
Comparator	2	2
AUSART/EUSART	1/0	0/1
Extended WDT	N	Y
Software Control Option of WDT/BOR	N	Y
INTOSC Frequencies	48 kHz or 4 MHz	31 kHz - 32 MHz
Clock Switching	Y	Y
Capacitive Sensing	N	Y
CCP/ECCP	2/0	2/2
Enhanced PIC16 CPU	N	Y
MSSPx/SSPx	0	2/0
Reference Clock	N	Y
Data Signal Modulator	N	Y
SR Latch	N	Y
Voltage Reference	N	Y
DAC	Y	Y